

Materials Development Corporation

21541 Nordhoff Street, #B, Chatsworth, CA 91311 - (818) 700-8290 - FAX (818) 700-8304

PRODUCT INFORMATION

MDC Model 323 WAFER AREA PROBER and HOT CHUCK SYSTEM For 300mm Wafers





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MDC Model 323 WAFER AREA PROBER and HOT CHUCK SYSTEM SPECIFICATIONS

Facility Requirements

Power: 110 to 120 VAC at 20 Amps, 50 to 60 Hz or 208 to 240 VAC at 10 Amps, 50

Hz

Coolant: Tap water at 1 to 2 gallons/minute (4 to 8 liters/minute) at 15 PSI (1.1

Kg/cm²).

Maximum Pressure of 20 PSI (1.4 Kg/cm²). No deionized water.

Vacuum: 20" to 25" (500 to 600mm) Hg.

Dimensions: Width 36" (91 cm); Depth 30" (76 cm); Height 38" (97 cm)

Communications

Protocol RS-232C Baud Rate 9600

Format: Asynchronous, 8 character bits, one stop bit, no parity

DC Heater Supply

Range: 0 to 100 Volts

AC Ripple: Less than 100 mV at temperature

Components:

- 300 mm (12") nickel plated chuck

Manual wafer pin liftLight tight enclosureSoftware controlled light

- Movable video microscope mount (does not include microscope)

- Model 490 QuietCHUCK DC Hot Chuck Controller

Instrumentation:

CSM/Win Systems from MDC are the ideal instruments to use with your Model 323 Wafer Area Probing System. CSM/Win Systems mate the most advanced C-V and I-V hardware with powerful Windows software to perform a wide variety of tests on semiconductors and MOS devices.

Options:

-Video Microscope System

-Stainless Steel Clean Room System Table

-CSM/Win System -Probe Multiplexers